

14230 U.S. PTO
07/31/03

PATENT APPLICATION
Docket No. 8750-045
Client No. SPX2003060020US

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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	DATE OF DEPOSIT: <u>JULY 31, 2003</u>
<p>I HEREBY CERTIFY THAT THIS PAPER AND ENCLOSURES AND/OR FEE ARE BEING DEPOSITED WITH THE UNITED STATES POSTAL SERVICE "EXPRESS MAIL POST OFFICE TO ADDRESSEE" SERVICE UNDER 37 CFR 1.10 ON THE DATE INDICATED ABOVE AND IS ADDRESSED TO: MAIL STOP PATENT APPLICATION, COMMISSIONER FOR PATENTS, P.O. BOX 1450, ALEXANDRIA, VA 22313-1450.</p>	
<u>JILL JEANS</u> (SENDER'S PRINTED NAME)	<u>Jill Jeans</u> (SIGNATURE)

Mail Stop Patent Application
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Enclosed for filing is a patent application under 37 CFR 1.53(b) of:

Inventor: In-Ku Kang, Hee-Kook Choi, Sang-Ho An and Sang-Yeop Lee

For: MULTI-CHIP MODULE HAVING BONDING WIRES AND METHOD OF FABRICATING THE SAME

Applicant requests FIG. 3 to be published with the application.

Enclosures:

- Specification (pages 1-7; claims (pages 8-11); abstract (page 12)
- THREE sheet(s) of FORMAL drawings (comprising 6 figures)
- PTO form 1449 Information Disclosure Statement with 4 cited references
- Return Postcard

<u>CLAIMS AS FILED</u>				
For	Number Filed	Number Extra	Rate	Basic Fee
Total Claims	25-20	5	x \$ 18 =	\$90.00
Independent Claims	3-3	0	x \$ 84 =	\$0.00
TOTAL FILING FEE				\$840.00

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07/31/03

Combined Declaration and Power of Attorney (unsigned)

Newly executed (original or copy)

Assignment with cover sheet

Assignee Name and Address:

Samsung Electronics Co., Ltd.

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Respectfully submitted,

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